

QFS-078-04.25-L-D-PC4

QFS-052-04.25-L-D-RF1

QFS-PC, QFS-RF SERIES

(0.635 mm) .025"

HIGH-SPEED COMBO RF & POWER

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?QFS

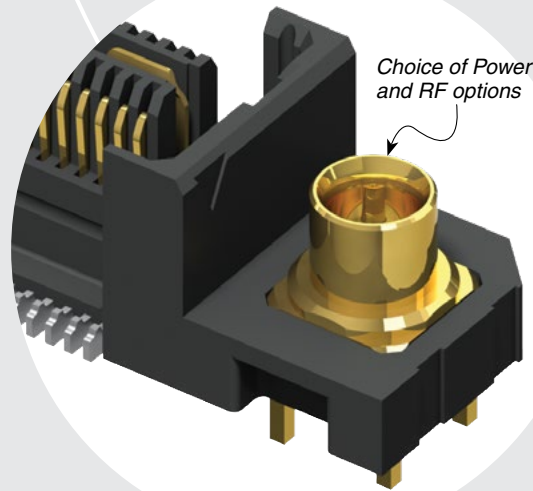
- Insulator Material:**
Liquid Crystal Polymer
Contact & Ground Plane Material:
Phosphor Bronze
Plating:
Au over 50 μ" (1.27 μm) Ni (Tin on Ground Plane Tail)
Current Rating:
Signal Contact:
2.6 A per pin (2 pins powered)
Power Contact:
4.0 A per pin (4 pins powered per end)
Ground Plane:
15.7 A per ground plane (1 ground plane powered)
Voltage Rating:
300 VAC mated with QMS
Operating Temp:
-55 °C to +125 °C
RoHS Compliant:
Yes

Board Mates:
QMS-PC, QMS-RA-PC, QMS-RF

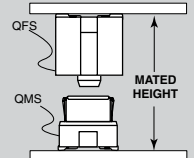
Standoffs:
SO

RUGGEDIZED
BY SAMTEC

- Increased insertion depth
- Integral guide post



APPLICATION



QMS LEAD STYLE	MATED HEIGHT*
-05.75	(10.00) .394
-06.75	(11.00) .433

*Processing conditions will affect mated height. See SO Series for board space tolerances.

PROCESSING

- Lead-Free Solderable:**
Yes
SMT Lead Coplanarity:
(0.10 mm) .004" max (026-078)
Board Stacking:
For applications requiring more than two connectors per board, contact ipg@samtec.com

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality

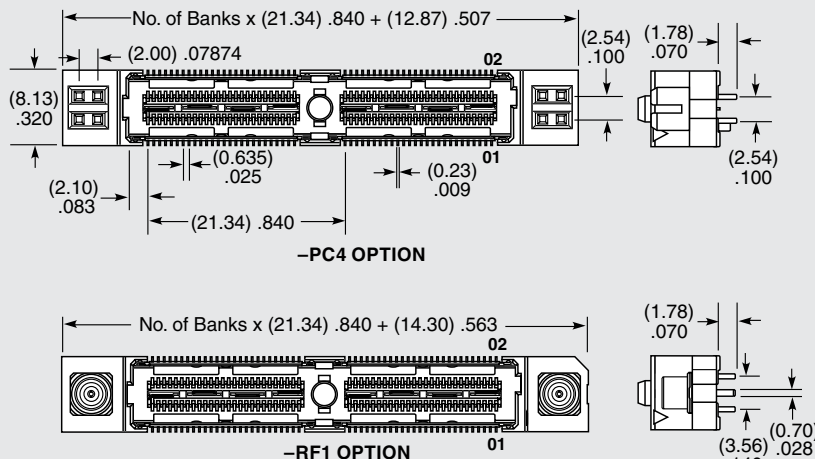


ALSO AVAILABLE (MOQ Required)

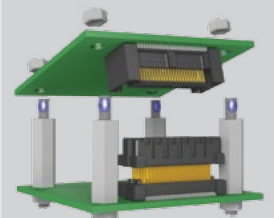
- Other platings
 - Differential Pairs
 - Retention Pins
 - 8 Power Pins/End for (1.60 mm) .062" thick board
 - 4 or 8 Power Pins/End for (2.36 mm) .093" thick board
 - 2 RF Connectors/End
 - Hot Pluggable
- Contact Samtec.

Note:
Some lengths, styles and options are non-standard, non-returnable.

QFS	NO. OF PINS PER ROW	LEAD STYLE	PLATING OPTION	D	END OPTION
	-026, -052, -078 (52 total pins per bank)	-04.25 = 04.25 mm	-L = 10 μ" (0.25 μm) Gold on Signal Pins and Ground Plane (Tin on Signal Pin tails, and Ground Plane tails)		-PC4 = 4 Power Pins per End for (1.60 mm) .062" thick Board (N/A with -RF1) -RF1 = One RF Jack per End (N/A with -PC4)



OTHER SOLUTIONS



See SO Series for precision machined standoffs.

Due to technical progress, all designs, specifications and components are subject to change without notice.